

CONTROL SIGNAL TRANSMITTING METHOD WITH PACKAGE POWER PIN AND RELATED INTEGRATED CIRCUIT PACKAGE STRUCTURE

ABSTRACT OF THE DISCLOSURE

5 A method and a device are disclosed for transmitting a control signal to an option
pad of an integrated circuit chip at its package level. The method includes the steps of:
electrically isolating one of a plurality of commonly connected power transmitting pins of
the integrated circuit package; connecting the electrically isolated power transmitting pin
to the option pad to thereby transmit a control signal from outside through the electrically
10 isolated power transmitting pin to the option pad.